ASSOCIATION CONNECTION ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				nder both This d	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mfg Information				
upplier Inform															
Company name*			Company unique ID			Ur	Unique ID Authority					Response Date*			
onsemi											2025-07-06				
Contact Name		Title - Contact			Ph	Phone - Contact*				Email - Contact*					
Product-Env-Stew	ards	Product Enviro Compliance			N	NA				Product-Env-Stewards@onsemi.com					
uthorized Repres	entative*	Title - Representative			Ph	Phone - Representative*				Email - Representative*					
Product-Env-Stew	ards	Product Enviro Compliance			N	NA				Product-Env-Stewards@onsemi.com					
Request	Requester Item Number		Number	Mfr Item Name		Е	Effective Date	ate Version Manufacturing S		Manufacturing Site	,	Weight*	UOM	Unit Type	
		NCV59801CMLADJT NCP59		NCP59801 AD slo	NCP59801 AD slew rate ADJ DFNW8 3x3		025-07-06		N	MY1		28.2	mg	Each	
Ianufacturing	Process Information	on													
Terminal Plating / Grid Array Material Termi			erminal Base Alloy J-STD-020 MSL R		-STD-020 MSL Ratin	g	Peak Process Body Temperature Max Time at Pe		re Max Time at Peak	Temperat	ure Numl	ber of Reflow Cyc	eles		
Matte Tin (Sn) - annealed		С	CU Alloy 1		[260	260 C 30		30	secon	ds 3			
omments															
vel 1 - maximum	time at peak temperature	during sol	dering is 10-3	0 seconds				_	_		_	_			
or more informat	ion regarding material co	mposition 1	please refer to	page 3	_	•					•		_	_	

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.38	mg	Supplier	Silicon (Si)	7440-21-3		0.38	mg
Die Attach	0.07	mg		Epoxy resin	proprietary data		0.0105	mg
			Supplier	Silver (Ag)	7440-22-4		0.056	mg
			Supplier	Bismaleimide	13676-54-5		0.0035	mg
Lead Frame	10.71	mg	Supplier	Silver (Ag)	7440-22-4		0.1834	mg
			Supplier	Tin (Sn)	7440-31-5		0.6417	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0202	mg
			Supplier	Chromium (Cr)	7440-47-3		0.0303	mg
			Supplier	Copper (Cu)	7440-50-8		9.8093	mg
Mold Compound-Black	15.76	mg	Supplier	Silica Amorphous (SiO2)	7631-86-9		1.182	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0788	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		12.5292	mg
			Supplier	EpoxyNovolaCresins (Cresolic)	64425-89-4		0.788	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		1.182	mg
Plating	0.1	mg	Supplier	Tin (Sn)	7440-31-5		0.1	mg
Wire Bond	1.18	mg	Supplier	Palladium (Pd)	7440-05-3		0.0295	mg
			Supplier	Gold (Au)	7440-57-5		0.0118	mg
			Supplier	Copper (Cu)	7440-50-8		1.1387	mg